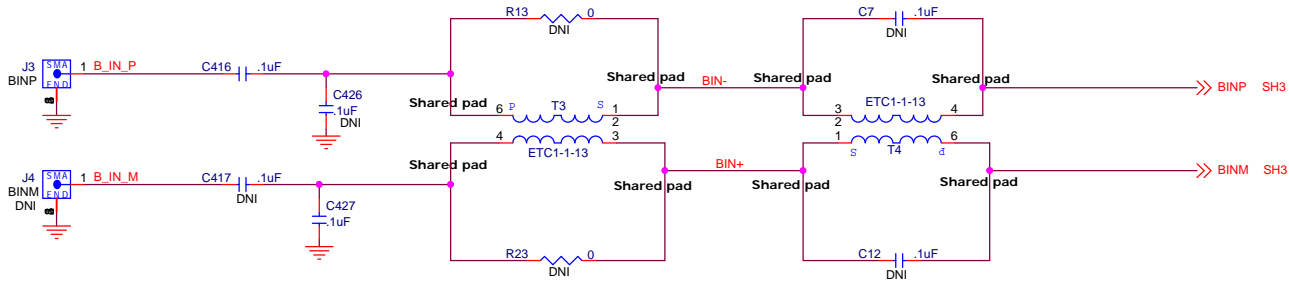
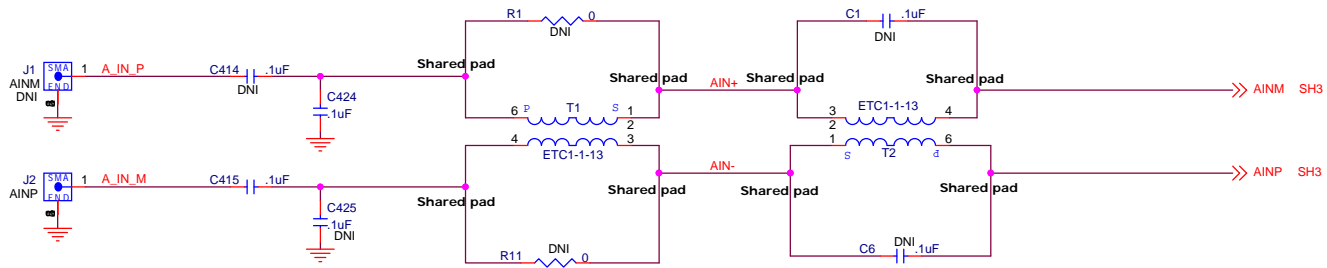


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BLOCK DIAGRAM


Engineer: R PRENTICE 8/2016	Size B	Document Number TIDA-01247 ADC32RFxxEVM	Rev E
PCB: L NGUYEN 08/2016	Date: Monday, August 21, 2017	Sheet 1 of 10	

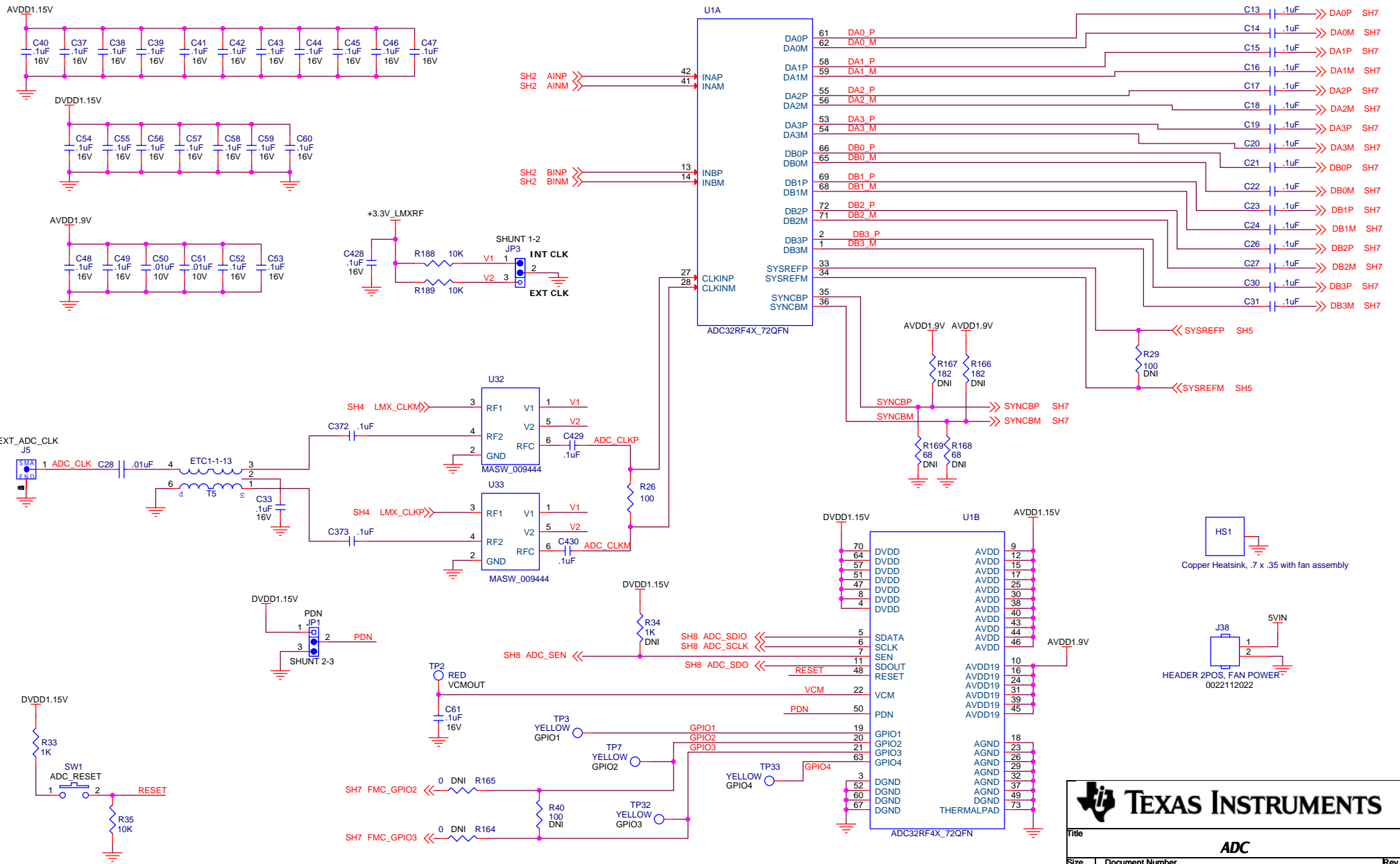


NOTE:

T1, T2, T3, T4 are TC1-1-43+ on ADC32RF80EVM
Value shown for ADC32RF45EVM

DNI = DO NOT INSTALL

 TEXAS INSTRUMENTS		
<small>2000-2016 TEXAS INSTRUMENTS CORPORATION</small>		
ANALOG IN		
Title B	Document Number ADC32RFxxEVM	Rev E
Date: Thursday, August 18, 2016 Sheet 2 of 10		

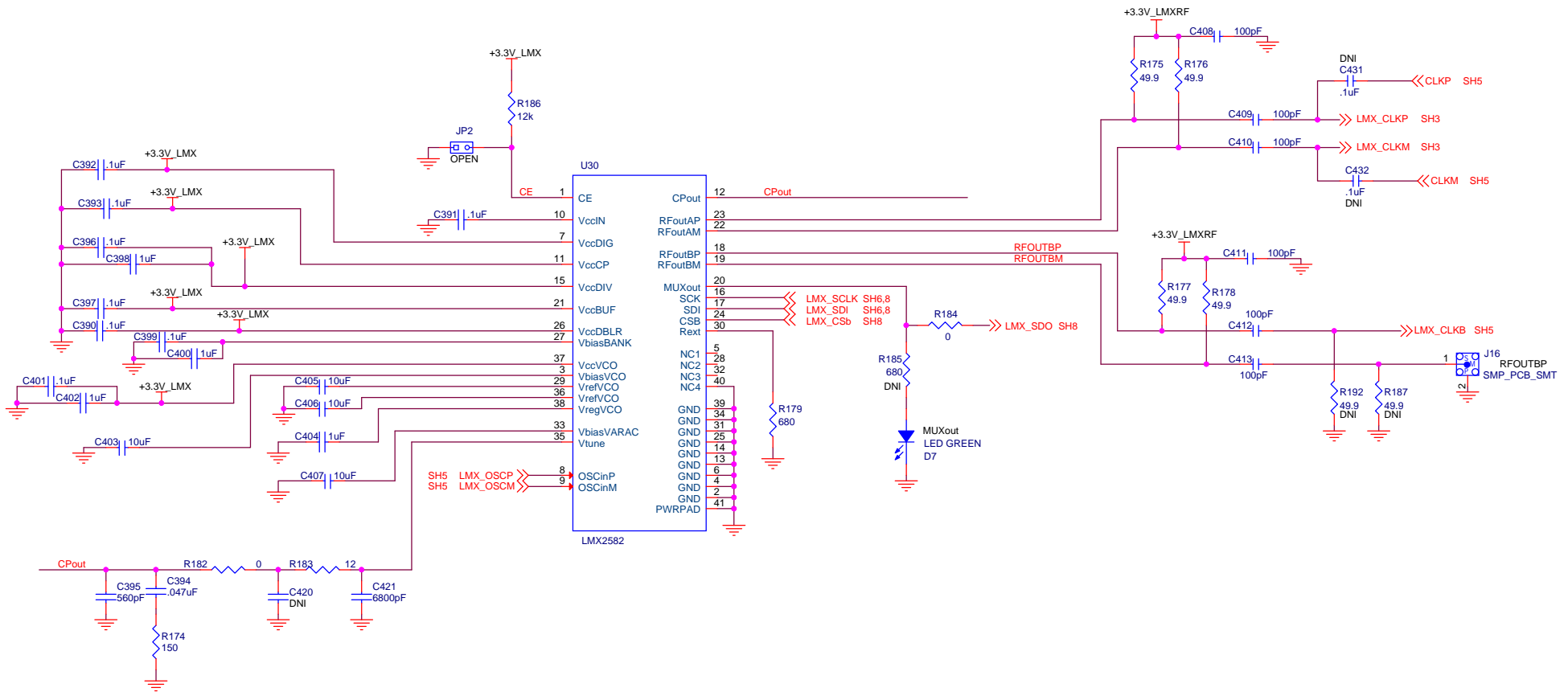


TEXAS INSTRUMENTS

Title: **ADC**

Size: **B** Document Number: **ADC32RFxxEVM** Rev: **E**

Date: Thursday, August 18, 2016 Sheet 3 of 10



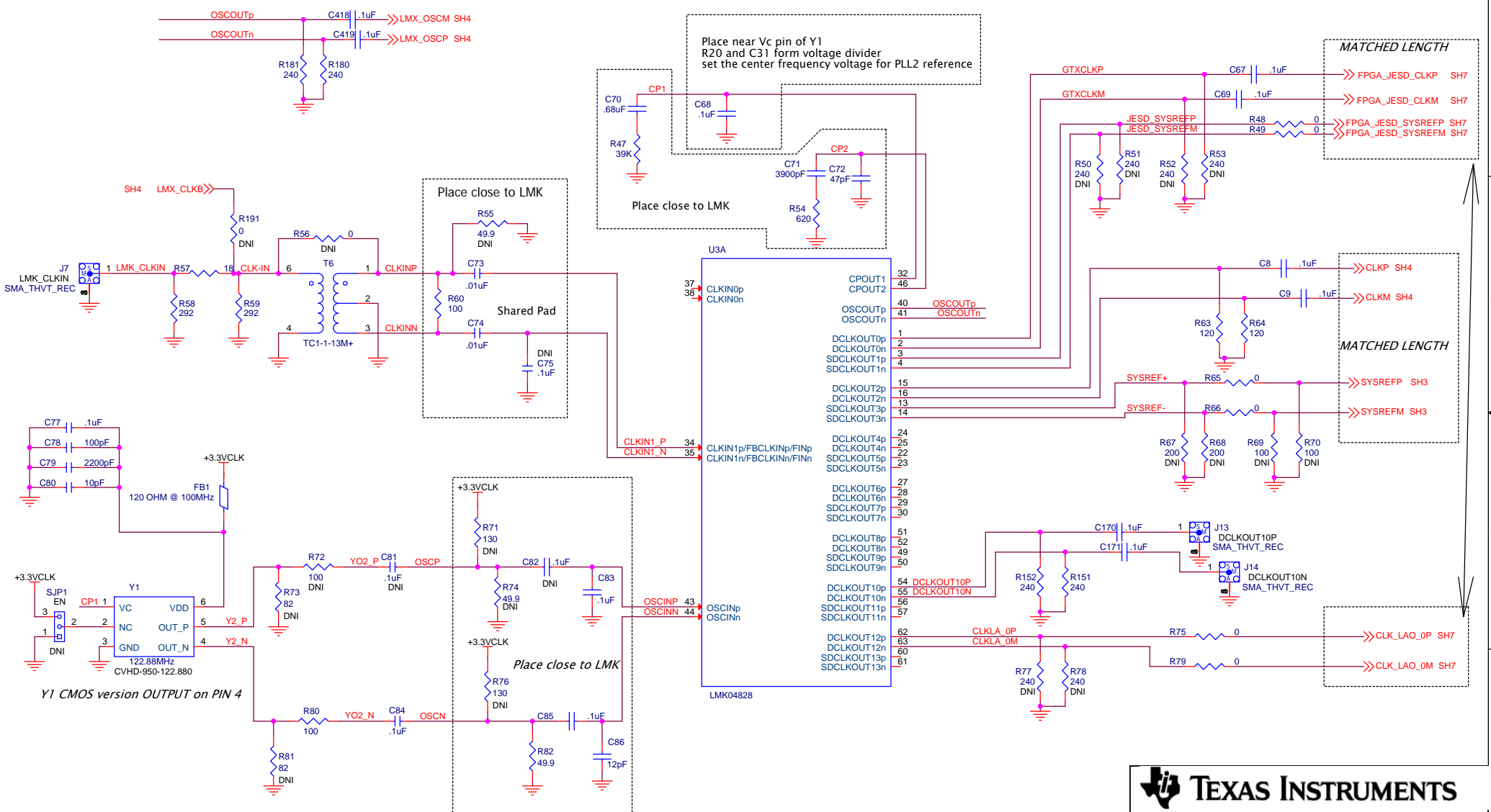
TEXAS INSTRUMENTS

Title 12500 11 Boulevard, Dallas, Texas 75243

LMX

Size B Document Number **ADC32RFxxEVM** Rev E

Date: Thursday, August 18, 2016 Sheet 4 of 10

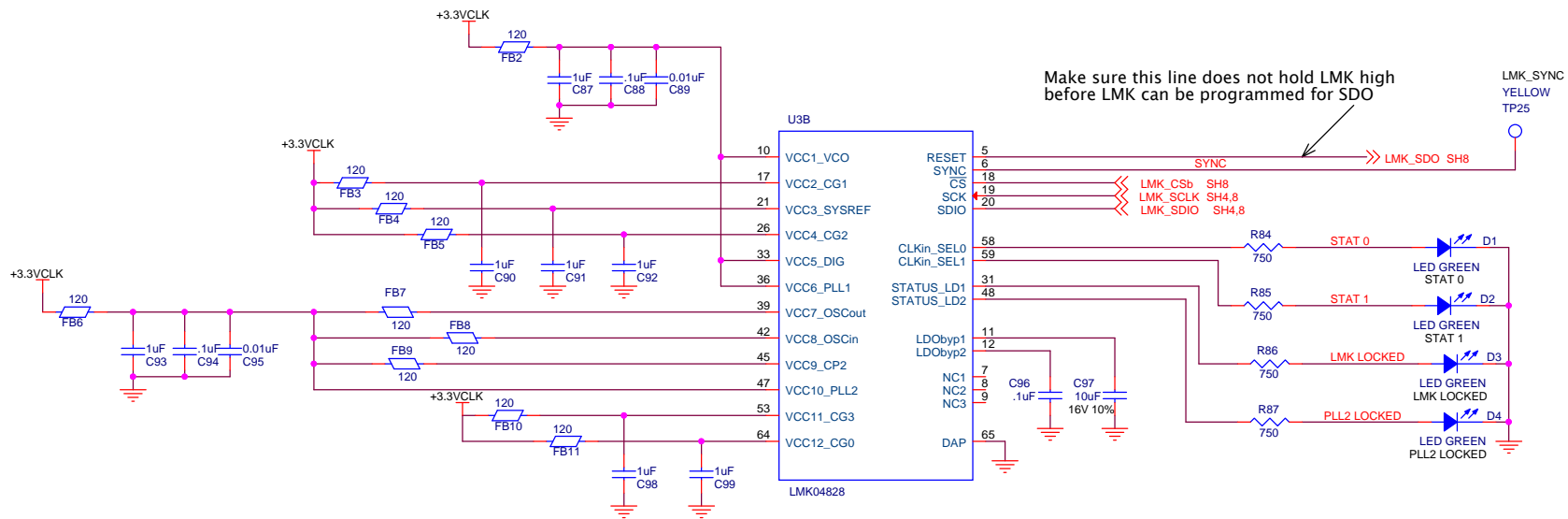


TEXAS INSTRUMENTS

Title: **LMK**

Size: **B** Document Number: **ADC32RFxxEVM** Rev: **E**

Date: Thursday, August 18, 2016 Sheet 5 of 10

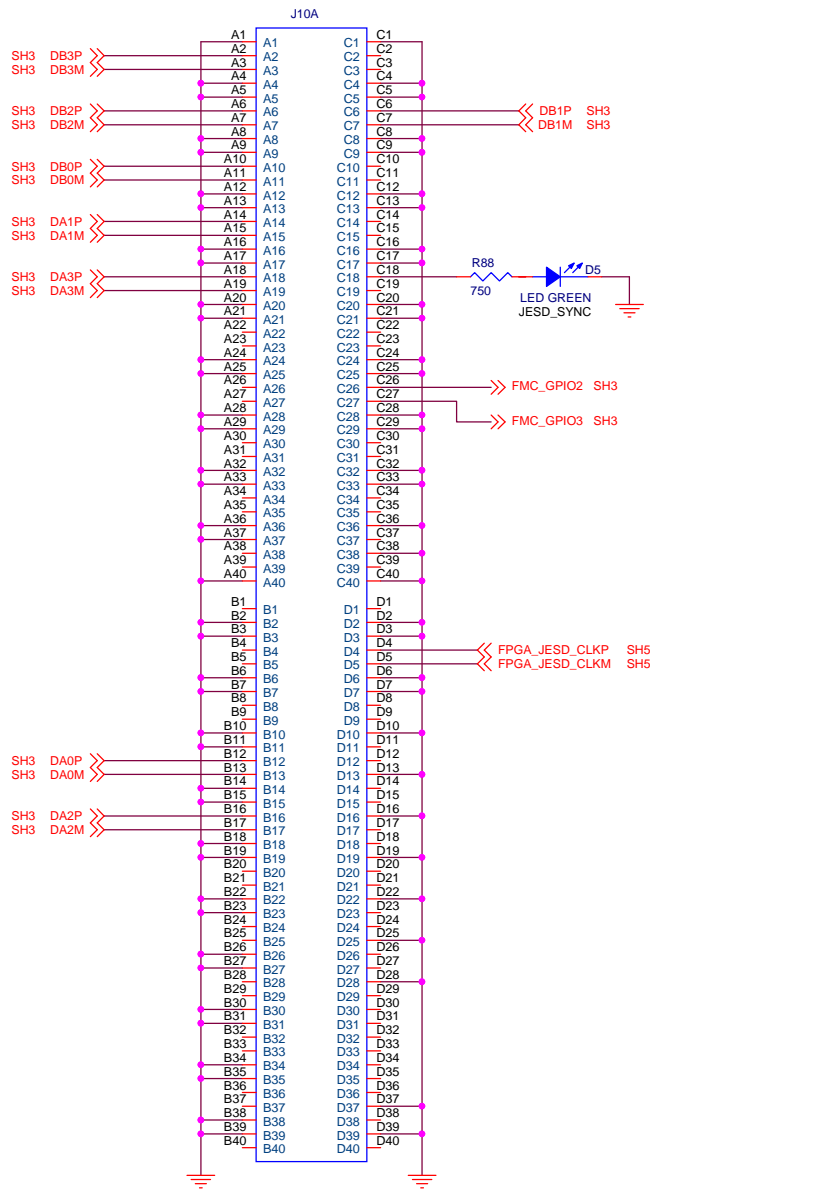


TEXAS INSTRUMENTS

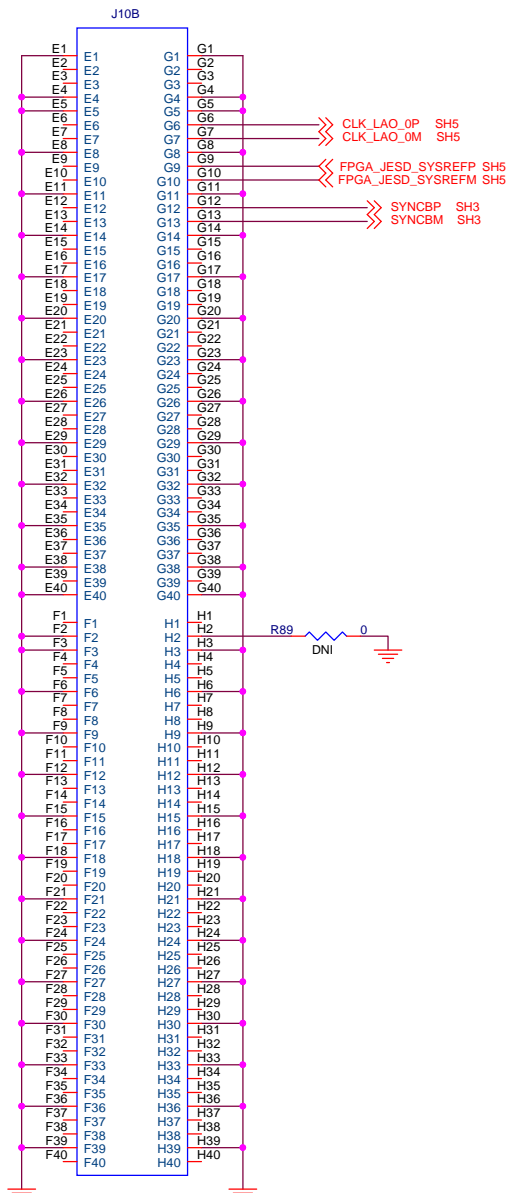
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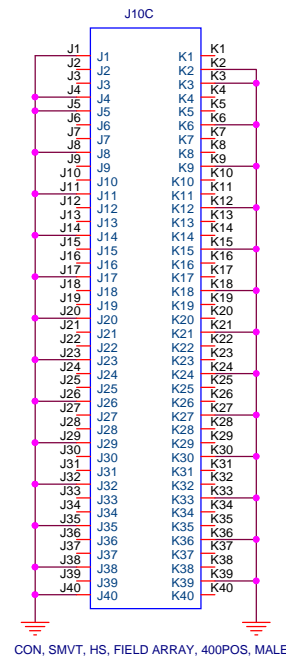
Date: Thursday, August 18, 2016 Sheet 6 of 10



CON, SMVT, HS, FIELD ARRAY, 400POS, MALE



CON, SMVT, HS, FIELD ARRAY, 400POS, MALE



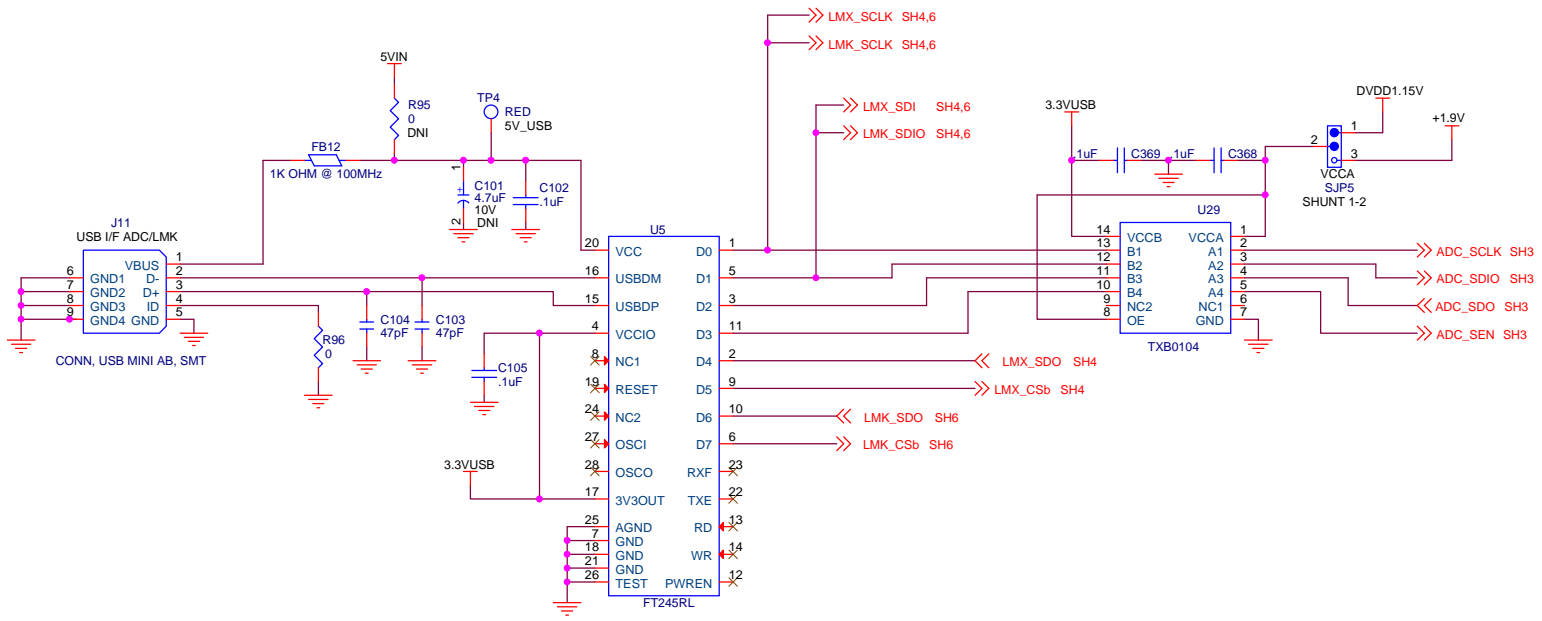
CON, SMVT, HS, FIELD ARRAY, 400POS, MALE

TEXAS INSTRUMENTS

Title: **USB**

Size: **B** Document Number: **ADC32RFxxEVM** Rev: **E**

Date: **Thursday, August 18, 2016** Sheet: **7** of **10**

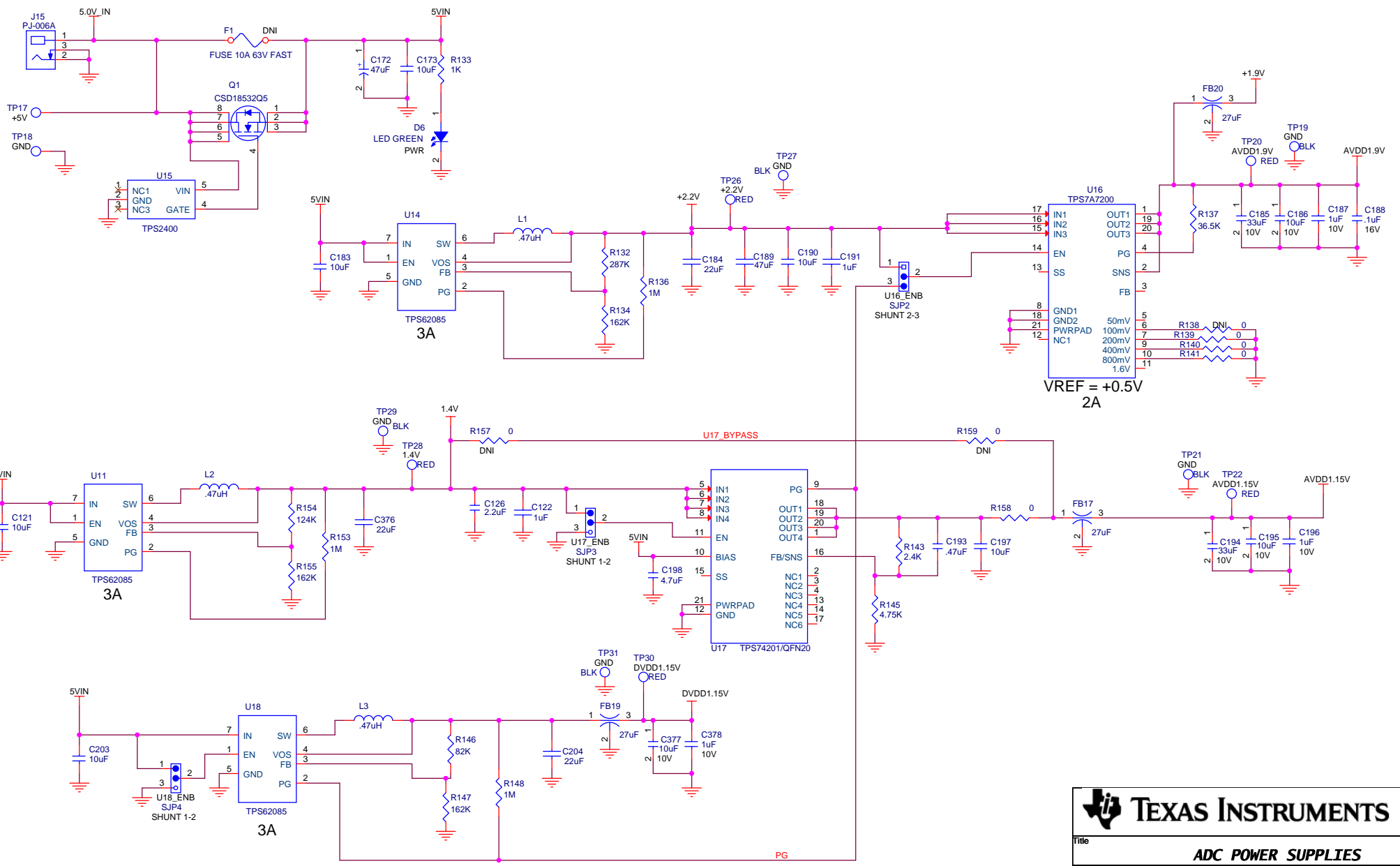


TEXAS INSTRUMENTS

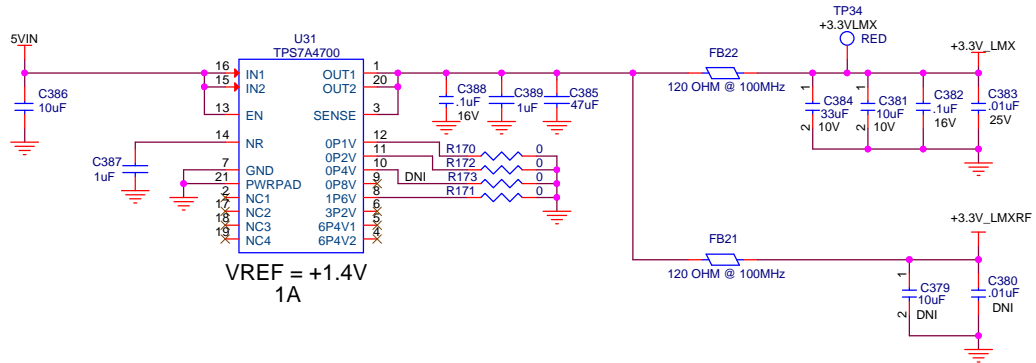
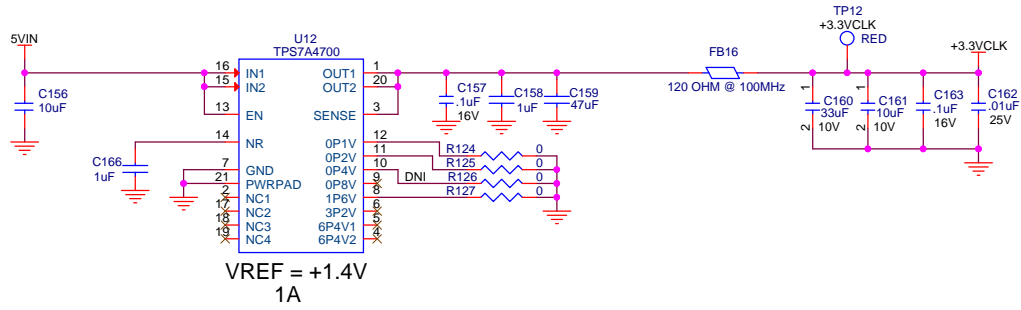
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Size: **B** Document Number: **ADC32RFxxEVM** Rev: **E**

Date: Thursday, August 18, 2016 Sheet 8 of 10

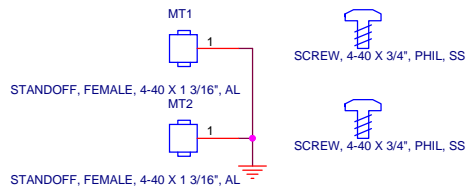


Title		
ADC POWER SUPPLIES		
Size	Document Number	Rev
B	ADC32RFxxEVM	E
Date:	Thursday, August 18, 2016	Sheet 9 of 10



MECHANICAL PARTS

BARE BOARD, ADC32RFXX



TEXAS INSTRUMENTS

Title		POWER SUPPLIES	
Size	Document Number	ADC32RFxxEVM	
B			Rev E
Date:	Thursday, August 18, 2016	Sheet 10	of 10

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